

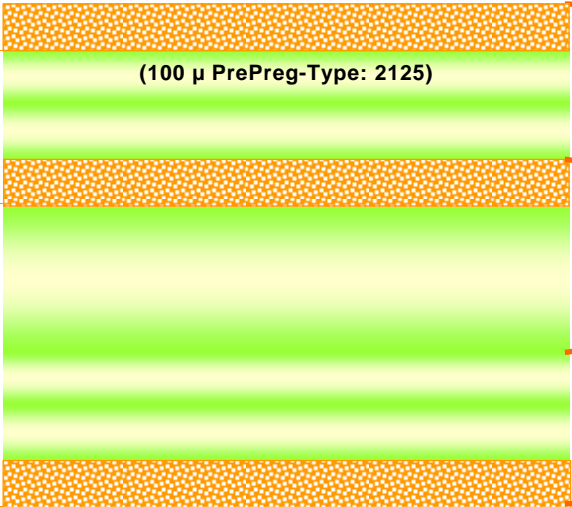
Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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03 154 FR4 55 L100.35 P10 s1

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

03_154_FR4_55_L100.35_p10_s1

Layers	in μ	Material	Build-Up	Assembly
Layer-1	55 μ	Copper		A1
	100 μ	Prepreg		
	100 μ	Prepreg		
Layer-2	35 μ	Copper		B
	1000 μ	L-FR4		
	100 μ	Prepreg		
Layer-99	100 μ	Prepreg		
	55 μ	Copper		

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